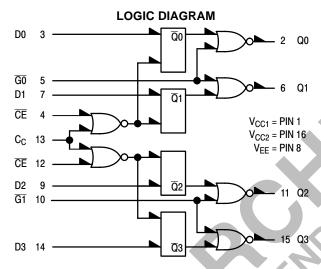
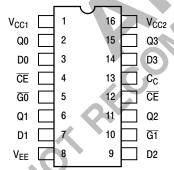
Quad Latch

The MC10153 is a high speed, low power, MECL quad latch consisting of four bistable latch circuits with D type inputs and gated Q outputs. Open emitters allow a large number of outputs to be wire-ORed together. Latch outputs are gated, allowing direct wiring to a bus. When the clock is low, outputs will follow D inputs. Information is latched on positive going transition of the clock. The MC10153 provides the same logic function as the MC10133, except for inversion of the clock.

- $P_D = 310 \text{ mW typ/pkg (No Load)}$
- $t_{pd} = 4.0 \text{ ns typ}$
- t_r , $t_f = 2.0$ ns typ (20%–80%)



DIP PIN ASSIGNMENT



Pin assignment is for Dual-in-Line Package.
For PLCC pin assignment, see the Pin Conversion Tables on page 18 of the ON Semiconductor MECL Data Book (DL122/D).

TRUTH TABLE

G	С	D	Q _{n+1}
Н	Х	Χ	L
L	Н	Χ	Q_n
L	L	L	L
L	L	Н	Н

 $C = C_C + \overline{CE}$



ON Semiconductor

http://onsemi.com



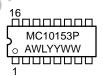


CDIP-16 L SUFFIX CASE 620





PDIP-16 P SUFFIX CASE 648





PLCC-20 FN SUFFIX CASE 775



A = Assembly Location

WL = Wafer Lot YY = Year WW = Work Week

ORDERING INFORMATION

Device	Package	Shipping
MC10153L	CDIP-16	25 Units / Rail
MC10153P	PDIP-16	25 Units / Rail
MC10153FN	PLCC-20	46 Units / Rail

ELECTRICAL CHARACTERISTICS

					-	Test Limits	3			
		Pin Under	-3	0°C		+25°C		+85	5°C	
Characteristic	Symb		Min	Max	Min	Тур	Max	Min	Max	Unit
Power Supply Drain Curr	ent I _E	8		83			75		83	mAdc
Input Current	l _{in} H	3 4 5 13		390 390 560 460			245 245 350 290		245 245 350 290	μAdc
	I _{inL}	3	0.5		0.5			0.3		μAdc
Output Voltage Log	gic 1 V _{OH}	2 2	-1.060 -1.060	-0.890 -0.890	-0.960 -0.960		-0.810 -0.810	-0.890 -0.890	-0.700 -0.700	Vdc
Output Voltage Log	gic 0 V _{OL}	2 2 2	-1.890 -1.890 -1.890	-1.675 -1.675 -1.675	-1.850 -1.850 -1.850		-1.650 -1.650 -1.650	-1.825 -1.825 -1.825	-1.615 -1.615 -1.615	Vdc
Threshold Voltage Log	gic 1 V _{OH}	2 2 2 2† 2‡ 2‡ 2 2	-1.080 -1.080 -1.080 -1.080 -1.080 -1.080 -1.080		-0.980 -0.980 -0.980 -0.980 -0.980 -0.980 -0.980 -0.980			-0.910 -0.910 -0.910 -0.910 -0.910 -0.910 -0.910 -0.910	S	Vdc
Threshold Voltage Log	gic 0 V _{OL} A	2 2 2 2† 2‡ 2‡		-1.655 -1.655 -1.655 -1.655 -1.655 -1.655		OP	-1.630 -1.630 -1.630 -1.630 -1.630 -1.630		-1.595 -1.595 -1.595 -1.595 -1.595 -1.595	Vdc
Switching Times (50 Ω L	oad)				0					ns
Propagation Delay	t ₃₊₂₊ t ₄₋₂₊ t ₅₋₂₊ t _{setup} t _{hold}	2 2 3	1.0 1.0 1.0 2.5 1.5	5.6 5.6 3.2	1.0 1.0 1.0 2.5 1.5	4.0 4.0 2.0 0.7 0.7	5.4 5.6 3.1	1.1 1.2 1.0 2.5 1.5	5.9 6.2 3.4	
Rise Time (20 to 8	60%) t ₂₊	2	1.0	3.6	1.1	2.0	3.5	1.1	3.8	
Fall Time (20 to 8	60%) t ₂₋	2	1.0	3.6	1.1	2.0	3.5	1.1	3.8	

Output level to be measured after a clock pulse has been applied to the clock input (Pin 4)	$oxed{ f L}_{-}^{f v}$	/ _{IHmax} /II min
	v	ııı mın

[‡] Data input at proper high/low level while clock pulse is high so that device latches ar proper high/low level for test. Levels are measured after device has latched.

* Latch set to zero state before test.

^{*} Latch set to zero state before test.

ELECTRICAL CHARACTERISTICS (continued)

				TEST VOLTAGE VALUES (Volts)					
		@ Test Te	mperature	V _{IHmax}	V_{ILmin}	V _{IHAmin}	V _{ILAmax}	V _{EE}	
			–30°C	-0.890	-1.890	-1.205	-1.500	-5.2	
			+25°C	-0.810	-1.850	-1.105	-1.475	-5.2	
			+85°C	-0.700	-1.825	-1.035	-1.440	-5.2	
			Pin	TEST \	OLTAGE A	PPLIED TO	PINS LISTED I	BELOW	
Characteristic	:	Symbol	Under Test	V _{IHmax}	V _{ILmin}	V _{IHAmin}	V _{ILAmax}	V _{EE}	(V _{CC}) Gnd
Power Supply Drain Curre	ent	ΙE	8		13			8	1, 16
Input Current		l _{inH}	3 4 5 13	3 4 5 13				8 8 8	1, 16 1, 16 1, 16 1, 16
		I _{inL}	3		3			8	1, 16
Output Voltage	Logic 1	V _{OH}	2 2	3 3	4 13			8 8	1, 16 1, 16
Output Voltage	Logic 0	V _{OL}	2 2 2	3,5	3,13 13 3,4			8 8 8	1, 16 1, 16 1, 16
Threshold Voltage	Logic 1	V _{ОНА}	2 2 2† 2† 2‡ 2; 2	3 3 3 3 3	4 4 4	ω O	4 13	8 8 8 8 8 8	1, 16 1, 16 1, 16 1, 16 1, 16 1, 16 1, 16 1, 16
Threshold Voltage	Logic 0	V _{OLA}	2 2 2 2† 2† 2‡ 2‡	3 3 3	4 4 4	5	3 13	8 8 8 8	1, 16 1, 16 1, 16 1, 16 1, 16 1, 16
Switching Times	(50Ω Load)		7.1	+1.11 V		Pulse In	Pulse Out	–3.2 V	+2.0 V
Propagation Delay		t_{3+2+} t_{4-2+} t_{5-2+} t_{setup} t_{hold}	2 2 2 3 3	3*		3 4 5 3 3	2 2 2 2 2	8 8 8 8	1, 16 1, 16 1, 16 1, 16 1, 16
Rise Time (20 to 80%)	t ₂₊	2			3	2	8	1, 16
Fall Time (20 to 80%)	t ₂₋	2			3	2	8	1, 16

[†] Output level to be measured after a clock pulse has been applied to the clock input (Pin 4) VILmin VILmin

Each MECL 10,000 series circuit has been designed to meet the dc specifications shown in the test table, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 linear fpm is maintained. Outputs are terminated through a 50-ohm resistor to -2.0 volts. Test procedures are shown for only one gate. The other gates are tested in the same manner.

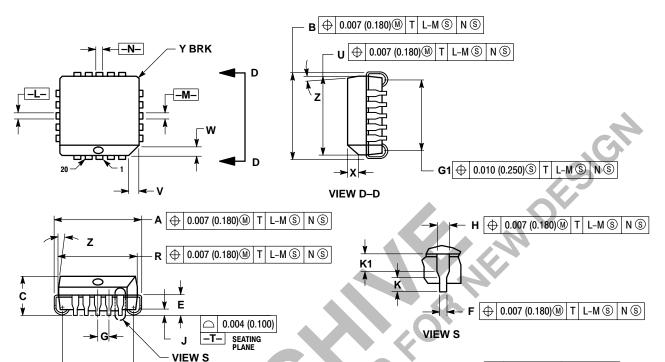
[‡] Data input at proper high/low level while clock pulse is high so that device latches ar proper high/low level for test. Levels are measured after device has latched.

^{*} Latch set to zero state before test.

PACKAGE DIMENSIONS

PLCC-20 **FN SUFFIX**

PLASTIC PLCC PACKAGE CASE 775-02 ISSUE C



NOTES:

G1 ⊕ 0.010 (0.250)③ T L-M ⑤ N ⑤

OF VICE NOT PRESCO

- IOTES:

 1. DATUMS -L-, -M-, AND -N- DETERMINED WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.

 2. DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM -T-, SEATING PLANE.

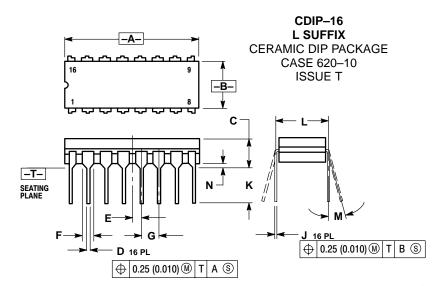
 3. DIMENSIONS R AND U DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.

 4. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M. 1982.
- Y14.5M, 1982. 5. CONTROLLING DIMENSION: INCH.
- THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT
- INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY. DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE

THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

	INC	HES	MILLIM	ETERS
DIM	MIN	MAX	MIN	MAX
Α	0.385	0.395	9.78	10.03
В	0.385	0.395	9.78	10.03
С	0.165	0.180	4.20	4.57
Е	0.090	0.110	2.29	2.79
F	0.013	0.019	0.33	0.48
G	0.050	BSC	1.27	BSC
Н	0.026	0.032	0.66	0.81
J	0.020		0.51	
K	0.025		0.64	
R	0.350	0.356	8.89	9.04
U	0.350	0.356	8.89	9.04
٧	0.042	0.048	1.07	1.21
W	0.042	0.048	1.07	1.21
X	0.042	0.056	1.07	1.42
Υ		0.020		0.50
Z	2°	10°	2 °	10 °
G1	0.310	0.330	7.88	8.38
K1	0.040		1.02	

PACKAGE DIMENSIONS



NOTES:

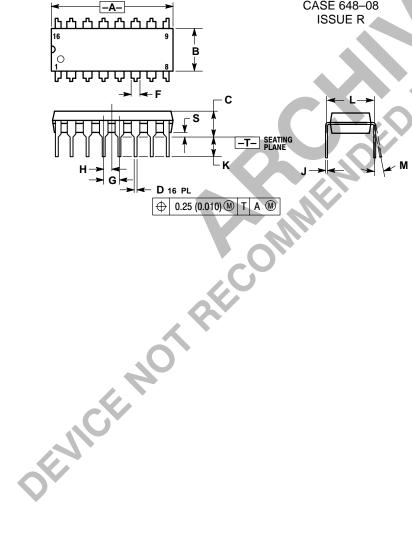
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: INCH.
 DIMENSION LTO CENTER OF LEAD WHEN CONTROLLING DIMENSION LTO CENTER OF LEAD WHEN

- FORMED PARALLEL

 DIMENSION F MAY NARROW TO 0.76 (0.030)
 WHERE THE LEAD ENTERS THE CERAMIC
 BODY.

	INC	HES	MILLIN	IETERS	
DIM	MIN	MAX	MIN	MAX	
Α	0.750	0.785	19.05	19.93	
В	0.240	0.295	6.10	7.49	
С		0.200		5.08	
D	0.015	0.020	0.39	0.50	
Е	0.050	BSC	1.27 BSC		
F	0.055	0.065	1.40	1.65	
G	0.100	.100 BSC 2.54		BSC	
Н	0.008	0.015	0.21	0.38	
K	0.125	0.170	3.18	4.31	
L	0.300 BSC		7.62	BSC	
М	0 °	15°	0 °	15°	
N	0.020	0.040	0.51	1.01	

PDIP-16 **P SUFFIX** PLASTIC DIP PACKAGE CASE 648-08



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
 4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
 5. ROUNDED CORNERS OPTIONAL

	INC	HES	MILLIN	IETERS	
DIM	MIN	MAX	MIN	MAX	
Α	0.740	0.770	18.80	19.55	
В	0.250	0.270	6.35	6.85	
C	0.145	0.175	3.69	4.44	
D	0.015	0.021	0.39	0.53	
F	0.040	0.70	1.02	1.77	
G	0.100	BSC	2.54 BSC		
Н	0.050	BSC	1.27	BSC	
J	0.008	0.015	0.21	0.38	
K	0.110	0.130	2.80	3.30	
L	0.295	0.305	7.50	7.74	
M	0°	10°	0°	10 °	
S	0.020	0.040	0.51	1.01	

Notes



Notes





ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer.

PUBLICATION ORDERING INFORMATION

Literature Fulfillment:

Literature Distribution Center for ON Semiconductor P.O. Box 5163, Denver, Colorado 80217 USA

Phone: 303–675–2175 or 800–344–3860 Toll Free USA/Canada **Fax**: 303–675–2176 or 800–344–3867 Toll Free USA/Canada

Email: ONlit@hibbertco.com

N. American Technical Support: 800-282-9855 Toll Free USA/Canada

JAPAN: ON Semiconductor, Japan Customer Focus Center 4–32–1 Nishi–Gotanda, Shinagawa–ku, Tokyo, Japan 141–0031

Phone: 81–3–5740–2700 **Email**: r14525@onsemi.com

ON Semiconductor Website: http://onsemi.com

For additional information, please contact your local

Sales Representative.